Characteristics STTH5R06

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Paran	Parameter				
V_{RRM}	Repetitive peak reverse voltage	Repetitive peak reverse voltage				
I _{F(RMS)}	Torruped tree current		TO-220AC TO-220FPAC D²PAK	20	А	
			DPAK	10		
I _{F(AV)}	Average forward current δ = 0.5, square wave	Tc = 135 °C	TO-220AC DPAK D²PAK	5	А	
		T _C = 105 °C	TO-220FPAC			
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal		50	Α	
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating junction temperature			175	°C	

Table 3: Thermal parameter

Symbol	Paran	Max. value	Unit	
R _{th(j-c)} Junction to case		TO-220AC / DPAK / D2PAK	3.0	°C ///
		TO-220FPAC	5.5	°C/W

Table 4: Static electrical characteristics

	Symbol	Parameter	Test cor	nditions	Min.	Тур.	Max.	Unit
Ī	ı (1)	Doverse leekage overent	T _j = 25 °C	\/ \/	-		20	
	I _R ⁽¹⁾	Reverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$	-	25	250	μA
Ī	V _F ⁽²⁾	Commend valtage drag	T _j = 25 °C		-		2.9	W
		Forward voltage drop	T _j = 125 °C	I _F = 5 A	-	1.4	1.8	\ \ \

Notes:

 $^{(1)}$ Pulse test: t_p = 5 ms, δ < 2%

(2)Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 1.164 \text{ x } I_{F(AV)} + 0.128 \text{ x } I_{F^{2}(RMS)}$

STTH5R06 Characteristics

Table 5: Dynamic electrical characteristics

Symbol	Parameter	Test conditions			Тур.	Max.	Unit
	Reverse recovery		I _F = 0.5 A I _{rr} = 0.25 A I _R = 1 A	-		25	
t _{rr}	time	T _j = 25 °C	$I_F = 1 \text{ A}$ $V_R = 30 \text{ V}$ $dI_F/dt = -50 \text{ A/}\mu\text{s}$	-		40	ns
I _{RM}	Reverse recovery current	I _F = 5 A		-	5.0	6.0	Α
Sfactor	Softness factor	T _j = 125 °C	T _j = 125 °C V _R = 400 V	-	0.35		-
Qrr	Reverse recovery charges	dI _F /dt = -200 A/μs		-	110		nC
t _{fr}	Forward recovery time	T 25 %C	I _F = 5 A	-		150	ns
V _{FP}	Forward recovery voltage	T_j = 25 °C V_{FR} = 1.1 x V_F (max.) dI_F/dt = 40 A/ μ s		-		4.5	V

Characteristics STTH5R06

Characteristics (curves) 1.1

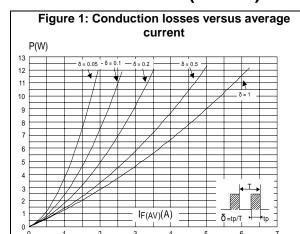


Figure 2: Forward voltage drop versus forward current 50 45 40 35 30 T_j= 125°C (typical values) 25 20 15 10 5 $V_F(V)$ 0 0 2 3 4 5 6

Figure 3: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC, DPAK, D2PAK)

1.0 $\frac{Z_{th(j-c)}/R_{th(j-c)}}{}$ 0.9 0.8 0.7 0.6 0.5 0.4 $\delta = 0.2$ 0.3 $-\delta = 0.1$ 0.2 0.1 tp(s) 0.0 1.E-03 1.E-02 1.E-01 1.E+00

junction to case versus pulse duration (TO-220FPAC) $1.0 \frac{Z_{th(j-c)}/R_{th(j-c)}}{}$ 0.9 8.0 0.7 0.6 0.5 0.4 0.3 _δ = 0.3 0.2 δ= 0. 0.1

tp(s)

1.E-01

1.E+00

1.E+01

0.0

1.E-03

1.E-02

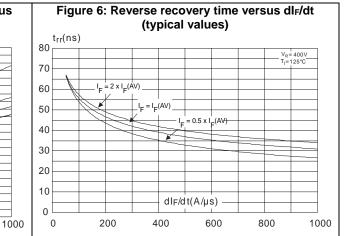
Figure 4: Relative variation of thermal impedance

Figure 5: Peak reverse recovery current versus dl_F/dt (typical values) 22 V_R=400\ T_j=125℃ 20 18 16 14 12 10 8 6

 $dIF/dt(A/\mu s)$

800

400



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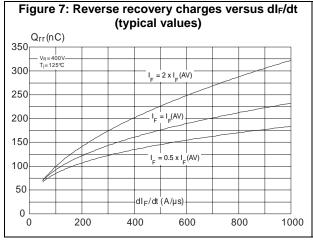
4

2

0

200

STTH5R06 Characteristics



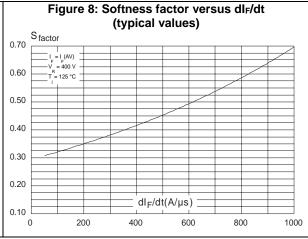
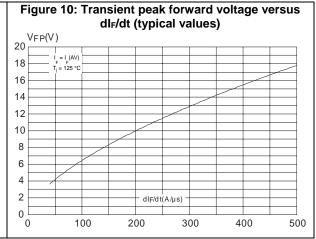
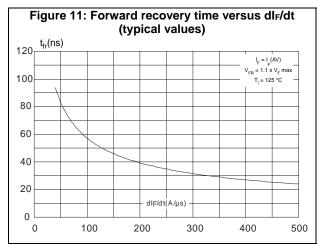
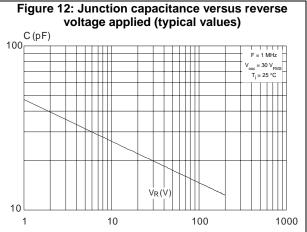


Figure 9: Relative variations of dynamic parameters versus junction temperature 2,50 2.25 2.00 1.75 1.50 1,25 1.00 0.75 I_{RM} 0.50 0.25 -Q_{RR} Reference:T_j = 125 °C _ T_j (°C)_ 0.00 50 75 100







Characteristics STTH5R06

Figure 13: Thermal resistance junction to ambient versus copper surface under tab (DPAK)

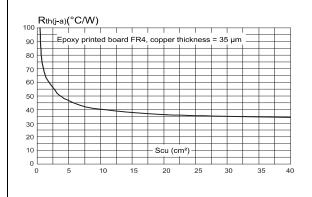
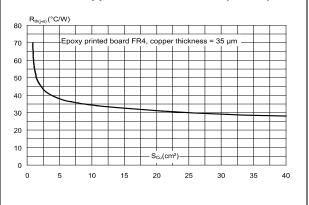


Figure 14: Thermal resistance junction to ambient versus copper surface under tab (D²PAK)



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2 **Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0
- Recommended torque value: 0.55 N·m (for TO-220FPAC / TO-220AC)
- Maximum torque value: 0.7 N·m (for TO-220FPAC / TO-220AC)

TO-220AC package information 2.1

H2 A **Diam** L5 L7 L6 L2 D F1 L9 L4 М Ε G

Figure 15: TO-220AC package outline



Table 6: TO-220AC package mechanical data

	Dimensions					
Ref.	Millin	neters	Inches			
	Min.	Max.	Min.	Max.		
A	4.40	4.60	0.173	0.181		
С	1.23	1.32	0.048	0.051		
D	2.40	2.72	0.094	0.107		
Е	0.49	0.70	0.019	0.027		
F	0.61	0.88	0.024	0.034		
F1	1.14	1.70	0.044	0.066		
G	4.95	5.15	0.194	0.202		
H2	10.00	10.40	0.393	0.409		
L2	16.40	O typ.	0.645	ō typ.		
L4	13.00	14.00	0.511	0.551		
L5	2.65	2.95	0.104	0.116		
L6	15.25	15.75	0.600	0.620		
L7	6.20	6.60	0.244	0.259		
L9	3.50	3.93	0.137	0.154		
М	2.6 typ.		0.102 typ.			
Diam	3.75	3.85	0.147	0.151		

2.2 TO-220FPAC package information

Figure 16: TO-220FPAC package outline

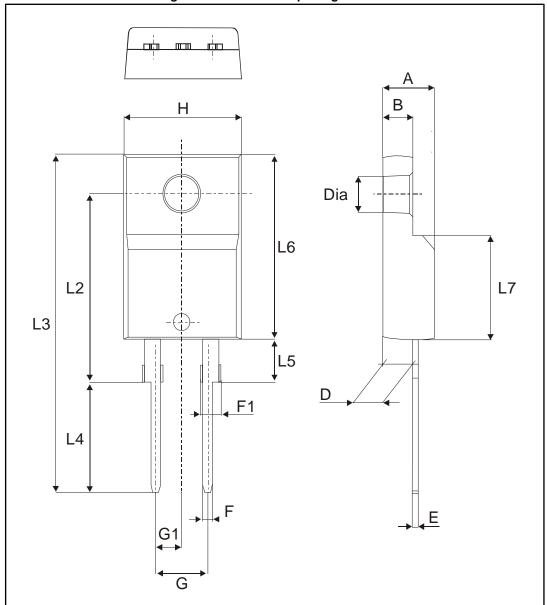


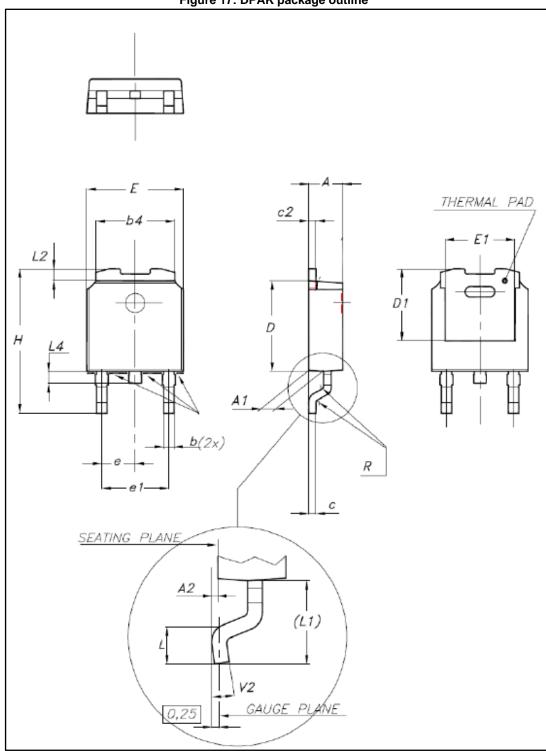
Table 7: TO-220FPAC package mechanical data

	Dimensions						
Ref.	Millim	neters	Incl	hes			
	Min.	Max.	Min.	Max.			
А	4.40	4.60	0.173	0.181			
В	2.50	2.70	0.098	0.106			
D	2.50	2.75	0.098	0.108			
Е	0.45	0.70	0.018	0.027			
F	0.75	1.00	0.030	0.039			
F1	1.15	1.70	0.045	0.067			
G	4.95	5.20	0.195	0.205			
G1	2.40	2.70	0.094	0.106			
Н	10.00	10.40	0.393	0.409			
L2	16.00	typ.	0.630 typ.				
L3	28.60	30.60	0.126	1.205			
L4	9.80	10.60	0.386	0.417			
L5	2.90	3.60	0.114	0.142			
L6	15.90	16.40	0.626	0.646			
L7	9.00	9.30	0.354	0.366			
Dia.	3.00	3.20	0.118	0.126			

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2.3 DPAK package information

Figure 17: DPAK package outline





This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

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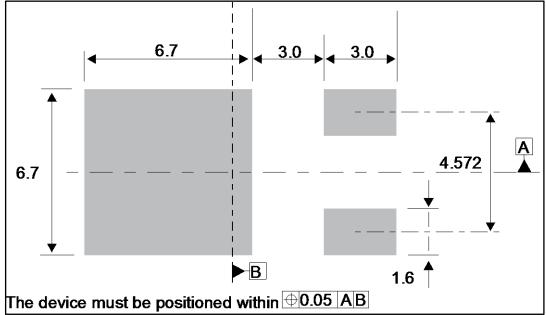
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Table 8: DPAK package mechanical data

		Din	nensions	
Ref.	Milli	Millimeters		hes
	Min.	Max.	Min.	Max.
А	2.18	2.40	0.085	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
b	0.64	0.90	0.025	0.035
b4	4.95	5.46	0.194	0.215
С	0.46	0.61	0.018	0.024
c2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	4.95	5.60	0.194	0.220
E	6.35	6.73	0.250	0.265
E1	4.32	5.50	0.170	0.216
е	2.2	86 typ.	0.09	0 typ.
e1	4.40	4.70	0.173	0.185
Н	9.35	10.40	0.368	0.409
L	1.0	1.78	0.039	0.070
L2		1.27		0.050
L4	0.60	1.02	0.023	0.040
V2	-8°	+8°	-8°	+8°

Figure 18: DPAK recommended footprint (dimensions in mm)



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2.4 D²PAK package information

Figure 19: D²PAK package outline

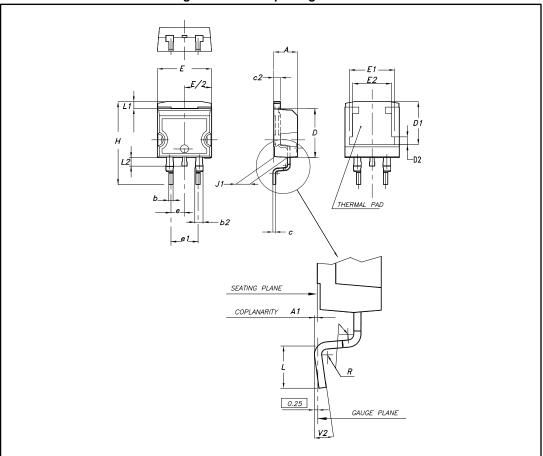




Table 9: D²PAK package mechanical data

	Dimensions						
Ref.		Millimeters	•		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	4.40		4.60	0.173		0.181	
A1	0.03		0.23	0.001		0.009	
b	0.70		0.93	0.028		0.037	
b2	1.14		1.70	0.045		0.067	
С	0.45		0.60	0.018		0.024	
c2	1.23		1.36	0.048		0.053	
D	8.95		9.35	0.352		0.368	
D1	7.50	7.75	8.00	0.295	0.305	0.315	
D2	1.10	1.30	1.50	0.043	0.051	0.060	
Е	10		10.40	0.394		0.409	
E1	8.50	8.70	8.90	0.335	0.343	0.346	
E2	6.85	7.05	7.25	0.266	0.278	0.282	
е		2.54			0.100		
e1	4.88		5.28	0.190		0.205	
Н	15		15.85	0.591		0.624	
J1	2.49		2.69	0.097		0.106	
L	2.29		2.79	0.090		0.110	
L1	1.27		1.40	0.049		0.055	
L2	1.30		1.75	0.050		0.069	
R		0.4			0.015		
V2	0°		8°	0°		8°	

9.75 16.9 1.6 2.54

Figure 20: D²PAK recommended footprint (dimensions are in mm)

Footprint

Ordering information STTH5R06

3 Ordering information

Table 10: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH5R06D	STTH5R06D	TO-220AC	1.90 g	50	Tube
STTH5R06G-TR	STTH5R06G	D²PAK	1.48 g	1000	Tape and reel
STTH5R06FP	STTH5R06FP	TO-220FPAC	1.90 g	50	Tube
STTH5R06B	STTH5 R06B	DPAK	0.30 g	75	Tube
STTH5R06B-TR	STTH5 R06B	DPAK	0.30 g	2500	Tape and reel

4 Revision history

Table 11: Document revision history

Date	Revision	Changes
17-Feb-2011	9	Last issue.
01-Aug-2014	10	Added insulated package text in <i>Features</i> . Corrected typographical errors in <i>Table 10</i> . Updated TO-220FPAC, D2PAK and DPAK package information and reformatted to current standard.
18-Sep-2014	11	Updated Figure 18, Figure 19 and Table 4.
19-Oct-2016	12	Updated DPAK package information and reformatted to current standard.

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